

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	9790	shigeru.in.	USPAT; US-PGPUB	2002/09/20 09:45
2	BRS	0	shigeru-ozora.in.	USPAT; US-PGPUB	2002/09/20 09:42
3	BRS	8	shigeru.in. and bump adj electrode	USPAT; US-PGPUB	2002/09/20 09:42
4	BRS	6	ozora.in.	USPAT; US-PGPUB	2002/09/20 09:46
5	BRS	3000	ando.in.	USPAT; US-PGPUB	2002/09/20 09:46
6	BRS	55	ando.in. and solder	USPAT; US-PGPUB	2002/09/20 09:49
7	BRS	16	takeda.in. and solder and bump	USPAT; US-PGPUB	2002/09/20 09:51
8	BRS	18	kamiya.in. and mitsubishi.as.	USPAT; US-PGPUB	2002/09/20 09:54
9	BRS	233	okamoto.in. and mitsubishi.as.	USPAT; US-PGPUB	2002/09/20 09:57
10	BRS	0	(okamoto.in. and mitsubishi.as.) and bonding adj pad	USPAT; US-PGPUB	2002/09/20 09:54
11	BRS	0	(okamoto.in. and mitsubishi.as.) and (bonding adj pad)	USPAT; US-PGPUB	2002/09/20 09:54
12	BRS	19	okamoto.in. and (bonding adj pad)	USPAT; US-PGPUB	2002/09/20 09:55
13	BRS	69	ono.in. and seiko.as.	USPAT; US-PGPUB	2002/09/20 09:58
14	BRS	1	(ono.in. and seiko.as.) and pad	USPAT; US-PGPUB	2002/09/20 09:58
15	BRS	7	(ono.in. and seiko.as.) and bonding	USPAT; US-PGPUB	2002/09/20 10:26
16	BRS	8	jp-62176140-\$.did. or jp-61-049452-\$.did. or jp-57106056-\$.did. or jp-05013418-\$.did. or jp-07335679-\$.did. or jp-60-007758-\$.did.	EPO; JPO; DERWENT	2002/09/20 10:05
17	IS&R	297	(257/781).CCLS.	USPAT; US-PGPUB	2002/09/20 10:05
18	BRS	2	jp-05166814-\$.did.	EPO; JPO; DERWENT	2002/09/20 12:35
19	BRS	1	jp-54043675-\$.did.	EPO; JPO; DERWENT	2002/09/20 12:57
20	IS&R	1	("6426555").PN.	USPAT; US-PGPUB	2002/09/20 12:57
21	BRS	12	("5149674" "5284797" "5661081" "5700735" "5834365" "5939335" "6124198" "6143646" "6163074" "6184141" "6198170" "6245683").PN.	USPAT	2002/09/20 12:57
22	BRS	9	blm! same (bonding! adj pad)	USPAT; US-PGPUB	2002/09/20 13:04

	Document ID	Pages	Title	Current OR	Current XRef	Inventor
1	US 6198170 B1	24	Bonding pad and support structure and method for their fabrication	257/784	257/781; 257/786; 438/612	Zhao, Bin
2	US 6433438 B1	41	Semiconductor integrated circuit device	257/776	438/197	Koubuchi, Yasushi et al.
3	US 6180504 B1	12	Method for fabricating a semiconductor component with external polymer support layer	438/612	257/668	Farnworth, Warren M. et al.
4	US 6179200 B1	10	Method for forming solder bumps of improved height and devices formed	228/254	228/174; 228/180.22; 228/248.1	Kung, Ling-Chen et al.

	D cument ID	Pages	Title	Current OR	Current XRef	Inventor
1	US 20010013657 A1	32	SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME	257/758	257/779; 257/781; 257/784; 257/786; 438/614; 438/617; 438/618	ANAND, MINAKSHISUNDARAN B.
2	US 20010011777 A1	7	Semiconductor device using a BGA package and method of producing the same	257/781	438/110; 438/612	Kano, Hideki
3	US 6426555 B1	7	Bonding pad and method for manufacturing it	257/734	257/779; 257/781; 257/782; 257/784; 257/786	Hsia, Chin Chiu et al.
4	US 6201305 B1	8	Making solder ball mounting pads on substrates	257/779	257/780; 257/781	Darveaux, Robert F. et al.
5	US 5854513 A	9	Semiconductor device having a bump structure and test electrode	257/737	257/734; 257/738; 257/763; 257/764; 257/766; 257/781; 257/786	Kim, Seong Jin